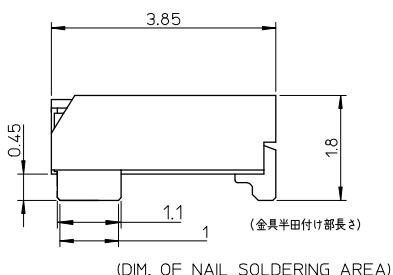
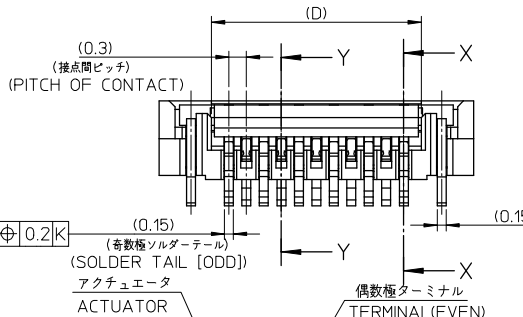
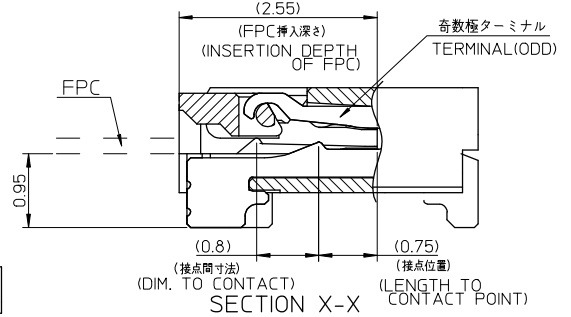
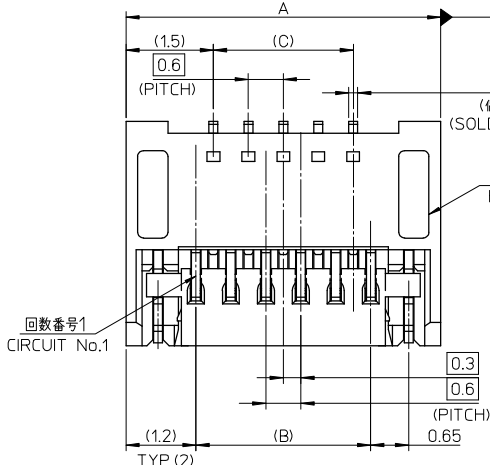


10 9 8 7 6 5 4 3 2 1

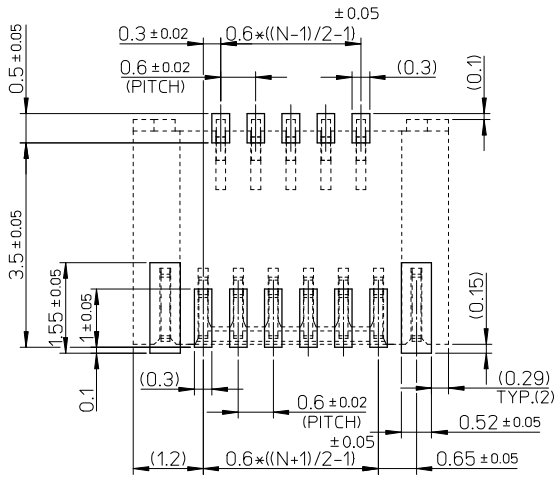


15.6	14.4	15.0	17.4	501912-5190	501912-5110	51
14.4	13.2	13.8	16.2	501912-4790	501912-4710	47
13.8	12.6	13.2	15.6	501912-4590	501912-4510	45
12.6	11.4	12.0	14.4	501912-4190	501912-4110	41
12.0	10.8	11.4	13.8	501912-3990	501912-3910	39
11.4	10.2	10.8	13.2	501912-3790	501912-3710	37
10.8	9.6	10.2	12.6	501912-3590	501912-3510	35
10.2	9.0	9.6	12.0	501912-3390	501912-3310	33
8.4	7.2	7.8	10.2	501912-2790	501912-2710	27
7.8	6.6	7.2	9.6	501912-2590	501912-2510	25
7.2	6.0	6.6	9.0	501912-2390	501912-2310	23
6.6	5.4	6.0	8.4	501912-2190	501912-2110	21
4.8	3.6	4.2	6.6	501912-1590	501912-1510	15
D	C	B	A	EMBOSSED-TAPE PKG ORDER No.	MATERIAL No.	CIRCUIT

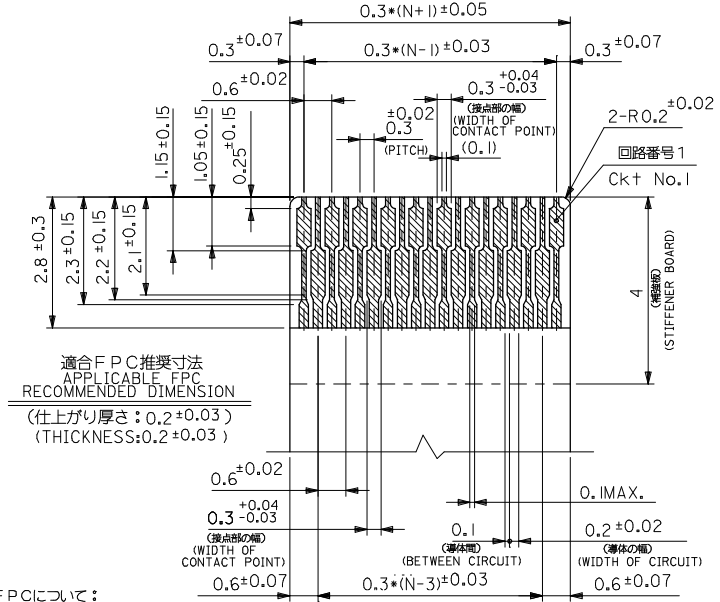
MODEL No. 501912-***10

REVISED EC NO: J2008-3324 TIDRWNHTAGAMI 2008/03/25 CHYKDKTAKAHASHI 2008/04/07 APPR:KIKAKAHASHI 2008/04/07 REV DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	TITLE 0.3 FPC CONN E/O HSG ASSY (HGT=1.8MM) GOLDPLATING MOLEX INCORPORATED MATERIAL NO. SEE TABLE DOCUMENT NO. SD-501912-001 SHEET NO. 1 OF 2
	10 UNDER	± 0.2	MM ONLY	15:1	METRIC	
	10 OVER 30 UNDER	± 0.25				
	30 OVER	± 0.3				
	ANGULAR ± 3 °					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						

10 9 8 7 6 5 4 3 2 1



参考基板レイアウト図
(マウント面)
(MOUNTING SIDE)



FPCについて:
打抜き方向は導体側から補強板側を推奨いたします。
導体部については軟銅箔35マイクロメートルまたは50マイクロメートルを推奨致します。
補強フィルム材質はポリイミドを推奨します。
接着剤は熱硬化接着剤を推奨します。

ABOUT FPC
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC :
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

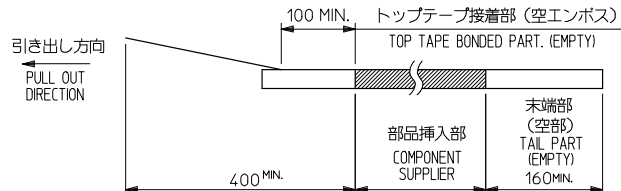
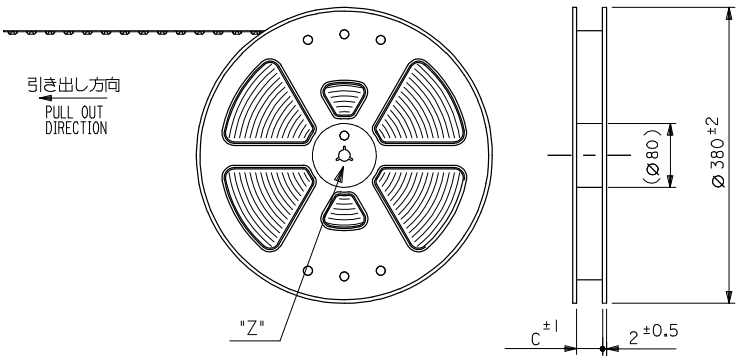
- 使用材料 MATERIAL
ハウジング : 耐熱性樹脂 ガラス充填 UL94V-0
HOUSING : HEAT RESISTANCE POLYMER (GLASS FILLED) UL94V-0
アクチュエータ : 耐熱性樹脂 ガラス充填 UL94V-0
ACTUATOR : HEAT RESISTANCE POLYMER (GLASS FILLED) UL94V-0
ターミナル : 銅合金 (t=0.15), ニッケル下地金メッキ
TERMINAL : COPPER ALLOY, GOLD OVER NICKEL PLATING.
金具 : 銅合金 (t=0.15), ニッケル下地スメッキ
FITTING NAIL : COPPER ALLOY, TIN OVER NICKEL PLATING.
ハウジングに黒点がある場合が有りますが、問題はありません。
- ソルダーテール半田付け面、及び金具半田付け面の平坦度: 0.1mm MAXIMUM.
COPLANARITY OF SOLDER TAILS AND FITTING NAILS TO BE 0.1mm MAXIMUM.
- ELV AND RoHS COMPLIANT.

REVISED EC NO: J2008-3324 TDRW:HTAGAMI 2008/03/25 CHKDK:TAKAHASHI 2008/04/07 APPR:K.TAKAHASHI 2008/04/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ----	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M.HAYASHI	DATE 2005/07/28	TITLE 0.3 FPC CONN E/O HSG ASSY (HGT=1.8MM) GOLDPLATING		
	10 OVER 30 UNDER	±0.25	CHECKED BY H.HIRATA	DATE 2005/07/28	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M.SASAO	DATE 2005/07/28	DOCUMENT NO. SD-501912-001		
	ANGULAR ±3 °	MATERIAL NO. SEE SHEET 1	SHEET NO. 2 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

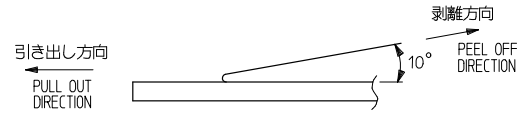
10 9 8 7 6 5 4 3 2 1

NOTES

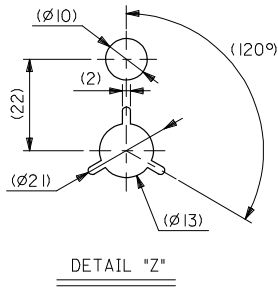
1. 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
2. 梱包数量：3000個/リール
NUMBER OF CONNECTORS : 3000PCS/REEL
3. リードテープ長さ LEAD TAPE LENGTH



4. トップテープの剥離強度：60±35gf (0.25N～0.93N) (剥離方向は下図参照) 尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 65gf±30gf (0.25N～0.93N) (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.) THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT. PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.

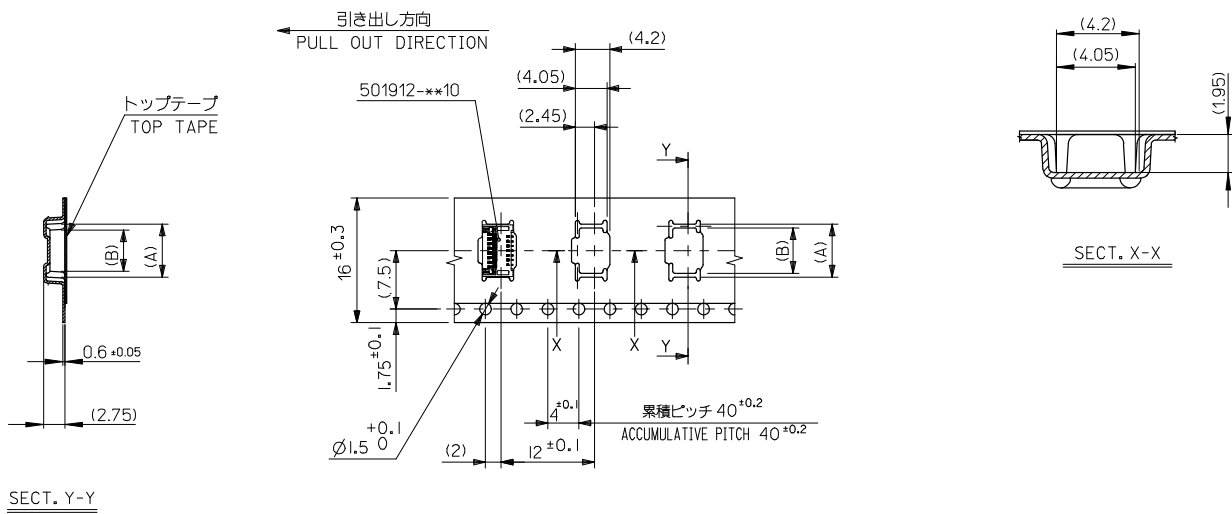


5. 材料(MATERIAL)
キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYRENE)
トップテープ (TOP TAPE) : PET, PE, PEF
リール(REEL) : ポリスチレン(PS) <リサイクル材を含む> POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>
6. C寸法は SHEET 2-4を参照下さい。
SEE SHEET 2-4(DIMENSION C).
7. ELV AND RoHS COMPLIANT.



REVISED EC NO: J2008-3324 T: DRW: HTAGAMI 2008/03/25 CHK: K: TAKAHASHI 2008/04/07 APP: R: TAKAHASHI 2008/04/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. 501912-***90
	10 UNDER	±0.2	DRAWN BY M. HAYASHI	DATE 2005/10/11	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING		
	10 OVER 30 UNDER	±0.25	CHECKED BY H. HIRATA	DATE 2005/10/11	THIRD ANGLE PROJECTION		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2005/10/11	MOLEX INCORPORATED		
	ANGULAR ±3°	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-501912-002		SHEET NO. 1 OF 4		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

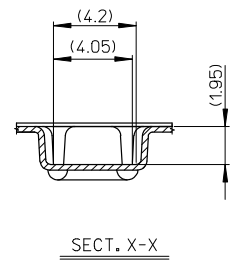
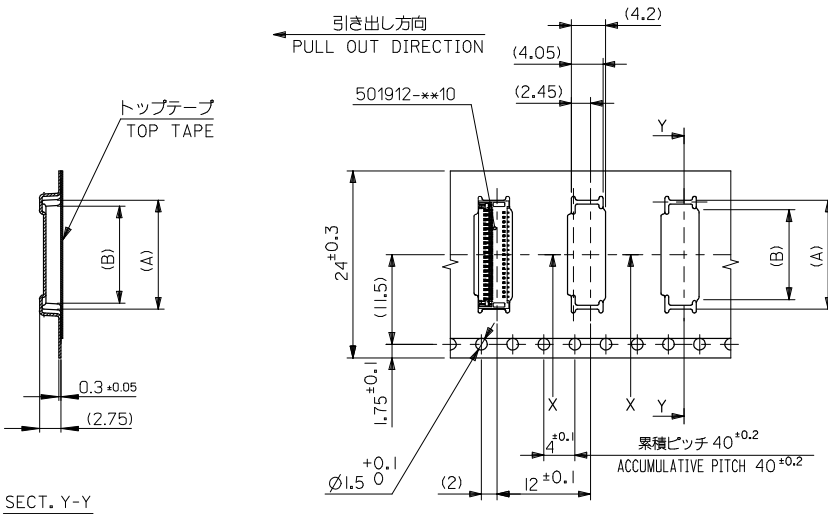


16 mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

16	17.5	4.6	6.8	501912-1590	15
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No.	極数 CK+
				501912-**-**90	MODEL No.

REVISED EC NO: J2008-3324 TIDRW:HTAGAMI 2008/03/25 CHYKOKI:KAKAHASHI 2008/04/07 APPR:K:KAKAHASHI 2008/04/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	MM ONLY	---	METRIC	
	10 OVER 30 UNDER	±0.25	DRAWN BY	TITLE		
	30 OVER	±0.3	M. HAYASHI	EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING		
	ANGULAR	±3 °	DATE	MOLEX INCORPORATED		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		2005/10/11	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
		2005/10/11	SEE TABLE	SD-501912-002	2 OF 4	
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

10 9 8 7 6 5 4 3 2 1



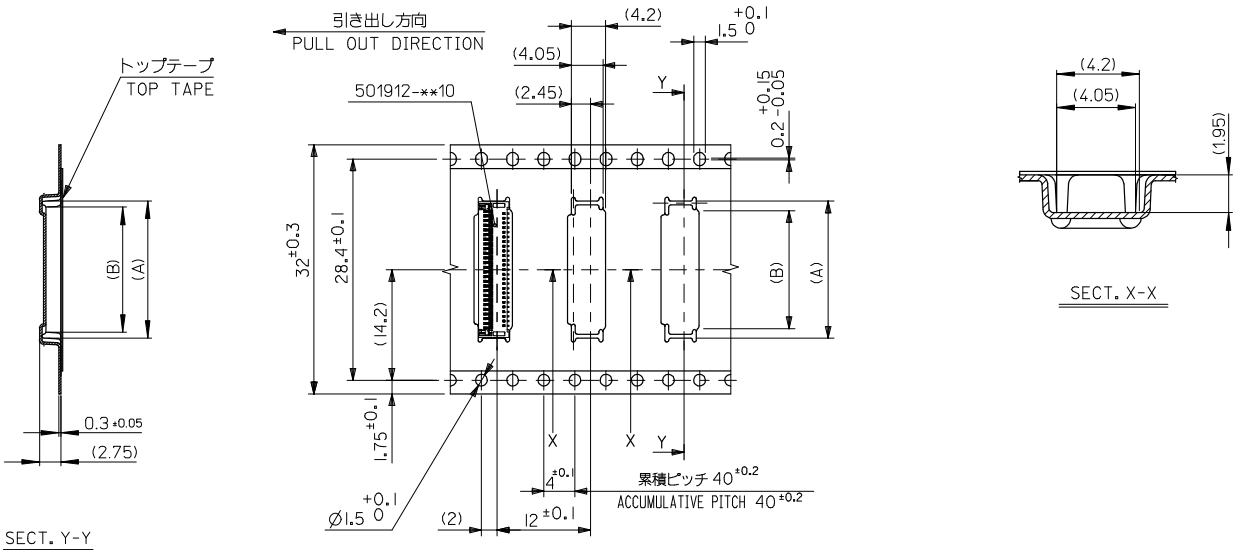
SECT. Y-Y

24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE

24	25.5	12.4	14.6	501912-4190	41
		11.8	14.0	501912-3990	39
		11.2	13.4	501912-3790	37
		10.6	12.8	501912-3590	35
		10.0	12.2	501912-3390	33
		8.2	10.4	501912-2790	27
		7.6	9.8	501912-2590	25
		7.0	9.2	501912-2390	23
6.4	8.6	501912-2190	21		
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No.	極数 CK+

REVISED J2008-3324 2008/03/25 TIDRWNHTAGAMI 2008/04/07 CHYKOKITAKAHASHI 2008/04/07 APPR:KTAHASHI 2008/04/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY M. HAYASHI	DATE 2005/10/11	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING		
	10 OVER 30 UNDER	±0.25	CHECKED BY H. HIRATA	DATE 2005/10/11	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2005/10/11	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-501912-002	SHEET NO. 3 OF 4
	ANGULAR ±3°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1



32mm幅キャリアテープ
32mm WIDTH CARRIER TAPE

32	33.5	15.4	17.6	501912-5190	51
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	14.2	501912-4790	47
		(A)	13.6	501912-4590	45
				製品番号 MATERIAL No.	極数 CK+
				501912-**-90	MODEL No.

REVISED EC NO: J2008-3324 T: DRWN: HTAGAMI 2008/03/25 CHYK: K: TAKAHASHI 2008/04/07 APPR: K: TAKAHASHI 2008/04/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	MM ONLY	---	METRIC	
	10 OVER 30 UNDER	±0.25	DRAWN BY	TITLE		
	30 OVER	±0.3	M. HAYASHI	EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING		
	ANGULAR	±3 °	DATE	MOLEX INCORPORATED		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
				SD-501912-002	4 OF 4	
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			